

ABSTRACT

Polyamide moulding compound, especially preferably as a transparent moulding with a high resistance to steam, containing at least one copolyamide formed at least from the polyamide units AB/AC/D, wherein

(A) is selected as at least one cycloaliphatic diamine from the group: bis(4-amino-3-methylcyclohexyl)methane (MACM) and bis(4-aminocyclohexyl)methane (PACM);

(B) is selected as at least one aromatic dicarboxylic acid from the group: isophthalic acid (I), naphthalenedicarboxylic acid, and terephthalic acid (T);

(C) is selected as at least one aliphatic dicarboxylic acid from the group: decanedioic acid, undecanedioic acid, dodecanedioic acid, tridecanedioic acid, tetradecanedioic acid, pentadecanedioic acid, hexadecanedioic acid;

(D) is selected as at least one lactam or α,ω -aminocarboxylic acid from the group: laurolactam (LC 12), undecanolactam (LC 11), 12-aminododecanoic acid, and 11-aminoundecanoic acid,

wherein

the proportions of polyamide units AB are in the range from 30 to 45 mol%,

the proportions of polyamide units AC are in the range from 30 to 40 mol%, and

the proportions of polyamide units D are in the range from 20 to 32 mol%,

and

wherein the sum total of polyamide units AB, AC and D is 100 mol%.

[Figure 1]